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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10024103	FILING DATE 12/17/2001	CLASS 438	SUBCLASS	GAU 2823	EXAMINER NGUYEN, K
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**APPLICANTS: Maruoka Michiaki;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
JAPAN 2000-394040 12/26/2000

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

NECB 19.265

TITLE : Semiconductor device having bonding pad electrode of multi-layer structure

U.S. DEPT. OF COMM./PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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